L	Hits	Search Text	DB	Time stamp
Number 1	2	("5889326").PN.	USPAT;	2004/09/10
*		(3009320).FN.	US-PGPUB;	09:16
			EPO; JPO;	05.10
			DERWENT;	
			IBM TDB	
2	9	, , = , = , = , = , = , = , = , = , = ,	USPAT	2004/09/10
		"5422516" "5508561" "5611481"		09:11
		"5640051" "5640052" "5641113").PN.		
3	27	5889326.URPN.	USPAT	2004/09/10
4	3540	((257/747) or (257/759) or (257/773) or	USPAT;	09:12
1	3310	(257/779)).CCLS.	US-PGPUB;	09:17
		(,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	EPO; JPO;	""
			DERWENT;	
			IBM_TDB	
5	5624	organic adj substrate	USPAT;	2004/09/10
			US-PGPUB;	09:17
			EPO; JPO;	
			DERWENT; IBM TDB	
6	60	(((257/747) or (257/759) or (257/773) or	USPAT;	2004/09/10
		(257/779)).CCLS.) and (organic adj	US-PGPUB;	09:28
		substrate)	EPO; JPO;	
			DERWENT;	
_	112	(257 (474) GGT G	IBM_TDB	2004/00/10
7	113	(257/474).CCLS.	USPAT; US-PGPUB;	2004/09/10
			EPO; JPO;	09:29
			DERWENT;	
			IBM TDB	1
8	256	(257/747).CCLS.	USPĀT;	2004/09/10
			US-PGPUB;	09:29
			EPO; JPO;	
			DERWENT; IBM TDB	
_	7	semiconductor adj substrate and organic	USPAT;	2004/09/10
		adj substrate and pad and solder and	US-PGPUB;	09:08
		("coefficent of thermal expansion" or	EPO; JPO;	
		cte)	DERWENT;	
		(454710004 460052024 460460104	IBM_TDB	2002/11/05
_	6	("5471090" "6005292" "6046910" "6118181" "6232668" "6271597").PN.	USPAT	2002/11/05
_	О	6310403.URPN.	USPAT	2002/11/05
				13:02
_	6	, , , , , , , , , , , , , , , , , , , ,	USPAT	2002/11/05
		"6118181" "6232668" "6271597").PN.		13:02
_	9		USPAT	2002/11/05
		"4949148" "5214308" "5302854" "5331513" "5528461" "5657207").PN.		13:02
_	5	"5331513" "5528461" "5657207").PN. 6046910.URPN.	USPAT	2002/11/05
				13:03
-	4345	"coefficent of thermal expansion" or cte	USPAT;	2002/11/05
		_	US-PGPUB;	13:16
			EPO; JPO;	
			DERWENT;	
_	31	((257/786).CCLS.) and ("coefficent of	IBM_TDB USPAT;	2002/11/05
		thermal expansion" or cte)	US-PGPUB;	13:06
		12 000,	EPO; JPO;	
			DERWENT;	
			IBM_TDB	0000 (45 (55
-	1299	c4 same solder	USPAT;	2002/11/05
			US-PGPUB; EPO; JPO;	13:07
			DERWENT;	
			IBM TDB	
	·		· -:	·

-	169	("coefficent of thermal expansion" or cte) and (c4 same solder)	USPAT; US-PGPUB;	2002/11/06 13:55
			EPO; JPO; DERWENT;	
			IBM_TDB	
-	327	gigapascal	USPAT;	2002/11/05
			US-PGPUB;	13:16
			EPO; JPO; DERWENT;	
			IBM TDB	
_	19	("coefficent of thermal expansion" or	USPAT;	2002/11/05
		cte) and gigapascal	US-PGPUB;	13:18
			EPO; JPO;	
			DERWENT;	
_	0	underfill adj material same gigapascal	IBM_TDB USPAT;	2002/11/05
		and graph and maderial banks graph bear	US-PGPUB;	13:19
			EPO; JPO;	
İ			DERWENT;	
	775		IBM_TDB	0000 (11 (05
-	775	underfill adj material	USPAT; US-PGPUB;	2002/11/05
			EPO; JPO;	13.13
			DERWENT;	
			IBM_TDB	
-	188	("coefficent of thermal expansion" or	USPAT;	2002/11/05
		cte) and (underfill adj material)	US-PGPUB;	13:19
			EPO; JPO; DERWENT;	
			IBM TDB	
-	143	conductive adj pad and solder and bump	USPAT;	2002/11/05
		and c4	US-PGPUB;	13:41
			EPO; JPO;	
			DERWENT; IBM TDB	
_	1235	(257/786).CCLS.	USPAT;	2002/11/06
			US-PGPUB;	09:10
			EPO; JPO;	
			DERWENT; IBM TDB	
_	195	c4 and solder and ("coefficent of thermal	USPAT;	2002/11/06
		expansion" or cte)	US-PGPUB;	13:51
			EPO; JPO;	
			DERWENT; IBM TDB	
_	7841	(lead adj base adj solder) or (lead-tin)	USPAT;	2002/11/06
		or (pb adj sn or pbsn)	US-PGPUB;	14:46
			EPO; JPO;	
			DERWENT;	1
_	20	("coefficent of thermal expansion" or	IBM_TDB USPAT;	2002/11/06
		cte) and (c4 same solder) and ((lead adj	US-PGPUB;	13:56
		base adj solder) or (lead-tin) or (pb adj	EPO; JPO;	
		sn or pbsn))	DERWENT;	
_	2570	(lead adj base adj solder) or (lead-tin)	IBM_TDB USPAT;	2002/11/06
	23,0	or (pb adj sn or pbsn) and c4	US-PGPUB;	15:00
			EPO; JPO;	
			DERWENT;	
_	14566	 flip add chip or flinchip	IBM_TDB USPAT;	2002/11/06
-	14200	flip adj chip or flipchip	USPAT; US-PGPUB;	14:47
			EPO; JPO;	
			DERWENT;	
	226	//1	IBM_TDB	2002/11/06
_	386	((lead adj base adj solder) or (lead-tin) or (pb adj sn or pbsn) and c4) and (flip	USPAT; US-PGPUB;	2002/11/06
		adj chip or flipchip)	EPO; JPO;	1 1 1 1 1
			DERWENT;	
			IBM TDB	1

-	245	((lead adj base adj solder) or (lead-tin)	USPAT;	2002/11/06
		or (pb adj sn or pbsn)) and c4	US-PGPUB;	15:01
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	69		USPAT;	2003/11/11
		solder	US-PGPUB;	10:14
	l		EPO; JPO;	
			DERWENT;	
			IBM_TDB	
-	6	("4673772" "5616520" "5761048"	USPAT	2003/11/11
	_	"5859407" "5907187" "6093964").PN.		10:23
_	1	6285083.URPN.	USPAT	2003/11/11
		5054454		10:25
_	2	6274474.URPN.	USPAT	2003/11/11
1		, , , , , ,		10:32
_	0	beriner.in.	USPAT;	2003/11/18
			US-PGPUB;	13:41
			EPO; JPO;	
			DERWENT;	
	670	bernier.in.	IBM_TDB	2002/11/10
_	6/0	bernier.in.	USPAT;	2003/11/18
			US-PGPUB;	13:41
			EPO; JPO;	
			DERWENT;	
	7	solder adj ball and bernier.in.	IBM_TDB USPAT;	2003/11/18
-	'	solder adj ball and bernier.in.	US-PGPUB;	13:43
			EPO; JPO;	13.43
			DERWENT;	
			IBM TDB	1
_	6925	carey.in. or gramatzki.in. or homa.in. or	USPAT;	2003/11/18
	0525	langevin.in. or tran.in. or white.in	US-PGPUB;	13:44
		rangeviniani or orani in or wire of in	EPO; JPO;	13
			DERWENT;	
			IBM TDB	
_	20	solder adj ball and (carey.in. or	USPAT;	2003/11/18
		gramatzki.in. or homa.in. or langevin.in.	US-PGPUB;	13:45
	ļ	or tran.in. or white.in)	EPO; JPO;	
		, '	DERWENT;	
			IBM_TDB	
] -	57	5075965.URPN.	USPĀT	2003/11/18
1				13:50
-	0	6330967.URPN.	USPAT	2003/11/18
				13:54
-	25	("4545610" "5060844" "5075965"	USPAT	2003/11/18
		"5161729" "5221038" "5234152"		13:54
		"5372298" "5429292" "5470787"		į į
		"5473814" "5580668" "5591941"		
		"5634268" "5639696" "5675889"		
		"5729896" "5796591" "5808853" "5025600" "5010505" "5050603"		
		"5825629" "5912505" "5953623" "5065045" "6121060" "6120476"		
		"5965945" "6121069" "6130476"		
		"6162660").PN.	HCDATE -	2004/00/02
-	27	organic adj substrate and (bump or	USPAT;	2004/09/03
		electrode or pad) and solder adj ball and	US-PGPUB;	14:30
		semiconductor adj substrate	EPO; JPO;	
			DERWENT;	
	I	l	IBM_TDB	<u> </u>